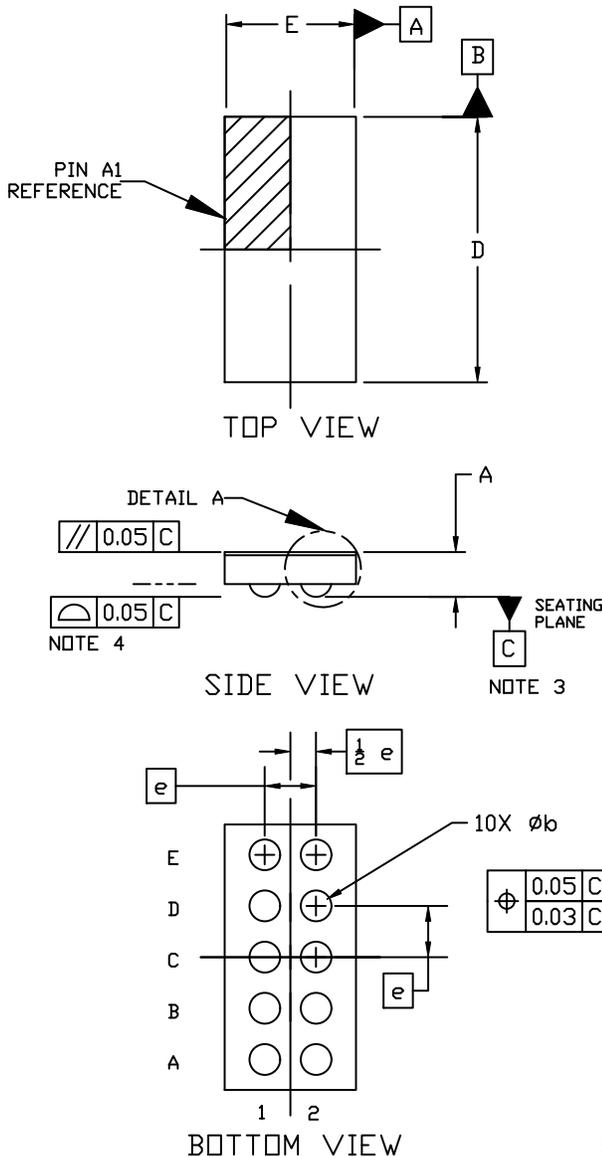




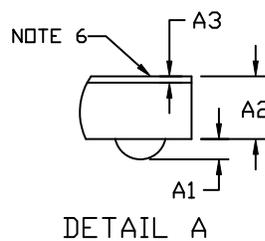
WLCSP10, 2.075x1.025x0.35
CASE 567ZC
ISSUE O

DATE 29 APR 2020

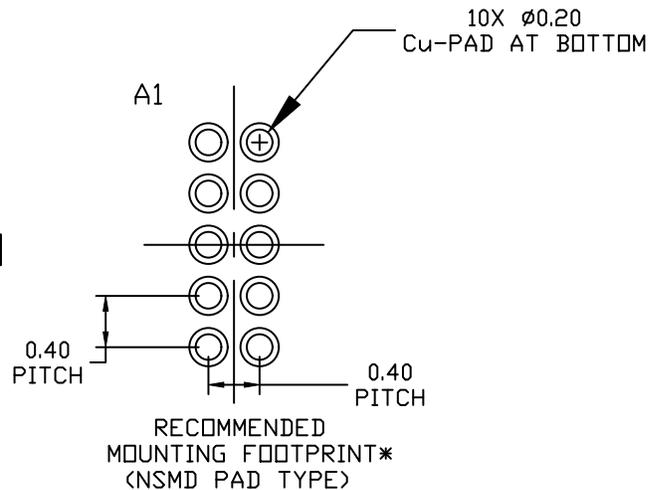


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. BACKSIDE COATING, IS OPTIONAL

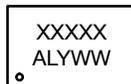


DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.310	0.350	0.390
A1	0.080	0.100	0.120
A2	0.25 REF		
A3	0.025 REF		
b	0.22	0.24	0.26
D	2.050	2.075	2.100
E	1.000	1.025	1.050
e	0.40 BSC		



* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

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